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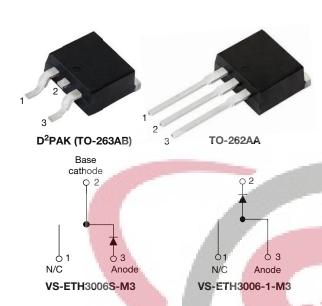
Vishay Semiconductors

COMPLIANT

HALOGEN

FREE

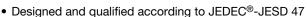
Hyperfast Rectifier, 30 A FRED Pt®



PRIMARY CHARACTE	RISTICS
I _{F(AV)}	30 A
V _R	600 V
V _F at I _F	1.4 V
t _{rr} (typ.)	27 ns
T _J max.	175 °C
Package	D ² PAK (TO-263AB), TO-262AA
Circuit configuration	Single

FEATURES

- Hyperfast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current



- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishav.com/dpc?99912

DESCRIPTION/APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 95 °C	30				
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	180	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-			
Converd veltage		I _F = 30 A	-	2.0	2.65	V		
Forward voltage	V_{F}	I _F = 30 A, T _J = 150 °C	-	1.4	1.8			
Develope legisere eviment		V _R = V _R rated	-	0.02	30			
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	50	300	μA		
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ		



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS						UNITS	
		$I_F = 1 \text{ A}, dI_F/dt = 5$	0 A/μs, V _R = 30 V	-	26	35		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	26		ns - A	
		T _J = 125 °C	I _F = 30 A dI _F /dt = 200 A/μs V _B = 200 V	-	70			
Dools recovery assurent	,	T _J = 25 °C		-	3.5	-		
Peak recovery current	I _{RRM}	T _J = 125 °C		-	7.6	-		
Dovorgo roccyony oborgo	0	T _J = 25 °C] "	-	50	-	nC	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	280	-	IIC	

THERMAL - MECHANICA	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C			
Thermal resistance, junction-to-case	R_{thJC}		1	0.95	1.4	°C/W			
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	4	-	70				
Thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased		0.5	-				
Weight			- 7	2.0	-	g			
weignt			-	0.07	-	oz.			
Mounting torque			6 (5)	3	12 (10)	kgf · cm (lbf · in)			
Madda da ta		Case style D ² PAK (TO-263AB)		ETH	ETH3006S				
Marking device		Case style TO-262AA	ETH3006-1						

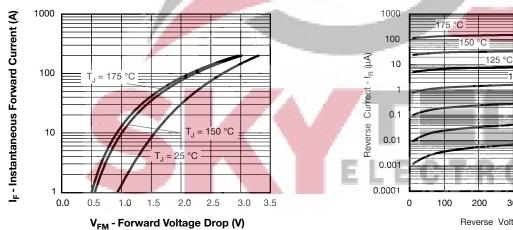


Fig. 1 - Typical Forward Voltage Drop Characteristics

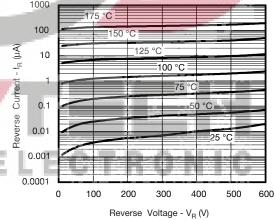


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

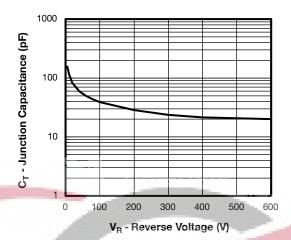


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

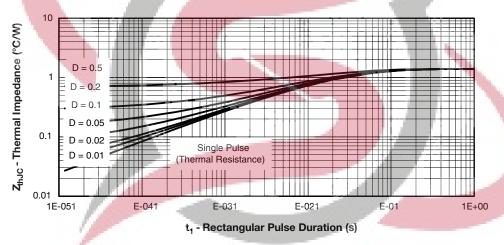


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

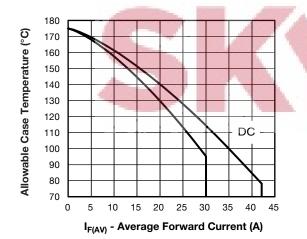


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

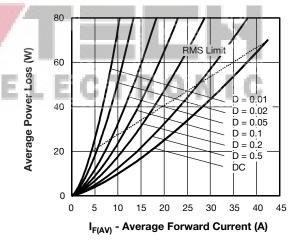


Fig. 6 - Forward Power Loss Characteristics

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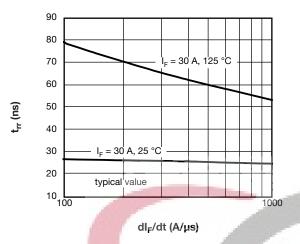


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

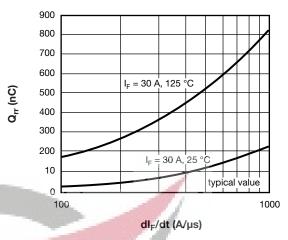
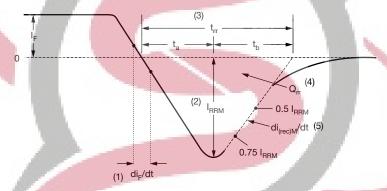


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

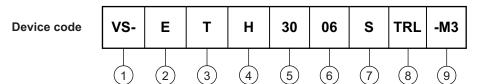
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ELECTRONIC



ORDERING INFORMATION TABLE



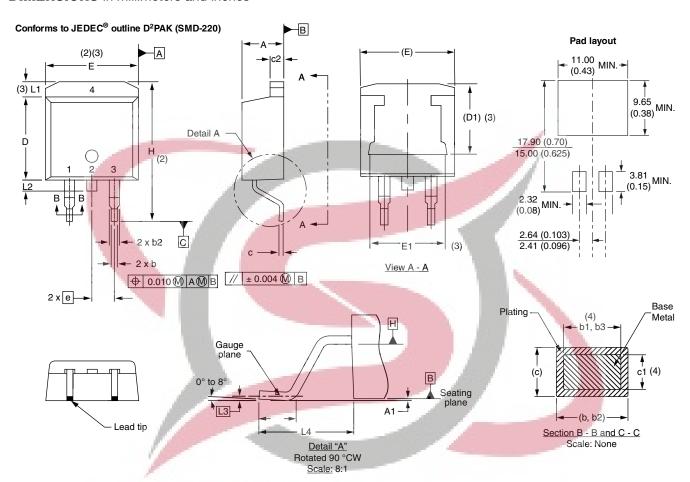
- 1 Vishay Semiconductors product
- 2 Circuit configuration
 - E = single
- 3 T = TO-220
- H = hyperfast recovery time
- 5 Current code (30 = 30 A)
- Voltage code (06 = 600 V)
- 7 $S = D^2PAK (TO-263AB)$
 - -1 = TO-262AA
- 8 None = tube (50 pieces)
 - • TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)
 - • TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)
- 9 -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-ETH3006S-M3	50	1000	Antistatic plastic tube				
VS-ETH3006-1-M3	50	1000	Antistatic plastic tube				
VS-ETH3006STRR-M3	800	800	13" diameter reel				
VS-ETH3006STRL-M3	800	800	13" diameter reel				

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Difficultions	TO-262AA	www.vishay.com/doc?96165				
B	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424				

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	400		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010	THE	7	E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	F	е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

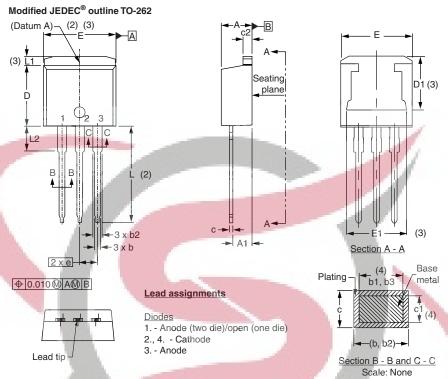
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164



TO-262AA

DIMENSIONS in millimeters and inches



CVMPOL	MILLIN	IETERS	INCH	IES	NOTES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190	9	
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070	U100	
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54	BSC	0.100	BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)

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